

CCDSC'14 Panel

Exascale topic

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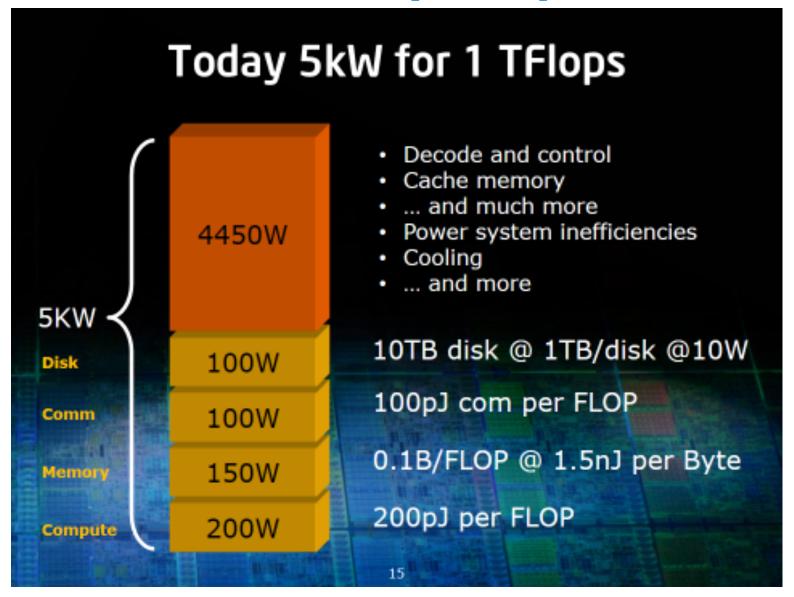
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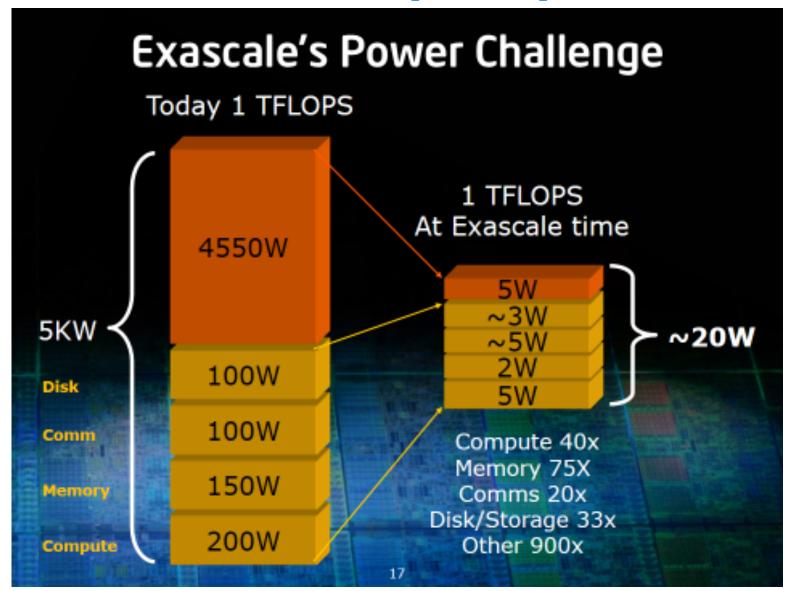


Problem statement (2011)





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1 EF (ExaFlops) = 10^{18} Flops

How can we achieve this?

It *could* take:

- A microarchitecture that does 10 ops/cycle 10^{1}

- In a core running at 2GHz

- With 250 cores per socket

- On a 200,000 sockets

2 10⁹ 2.5 10²

 $2 \ 10^5$

1 EF (ExaFlops) = 10^{18} Flops

How can we achieve this?

It *could* take:

_				1 A 1
- Δ	microarchitecture	that does 10	ons/cycle	10^{1}
	Thich but childeduic	tilat does to	ops/cycic	

- In a core running at 2GHz
- With 100 cores per socket
- On a 500,000 sockets

 2.10^9 10^2

 5.10^{5}

1 EF (ExaFlops) = 10^{18} Flops

How can we achieve this?

It *could* take:

- Δ	microar	chitecture	that does	10 o	ns/cycle	$\sim 10^{1}$
	IIICIUai	Cilitecture	triat does	TO O	ps/ cycle	

- In a core running at 1GHz
- With 500 cores per socket
- On a 200,000 sockets

2 10⁵

10⁹

 $5 10^2$

1 EF (ExaFlops) = 10^{18} Flops

How can we achieve this?

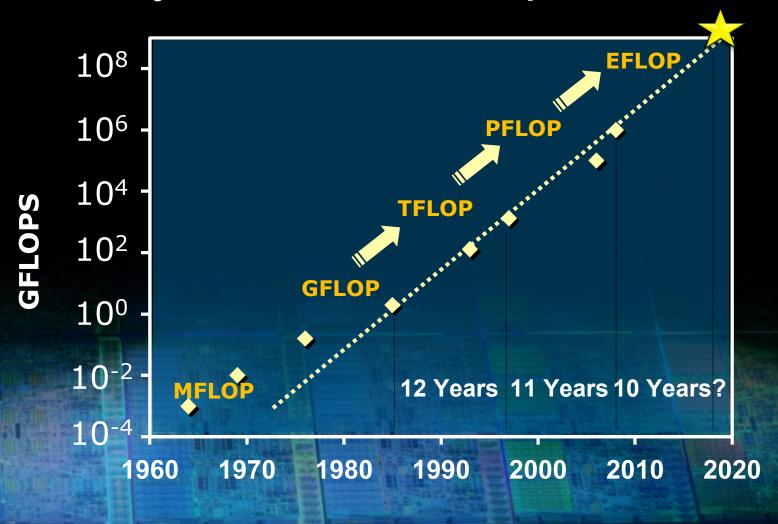
It *could* take:

- A microarchitecture that does 10 ops/cycle	TO-
- In a core running at 1GHz	10 ⁹
- With 1,000 cores per socket	10 ³

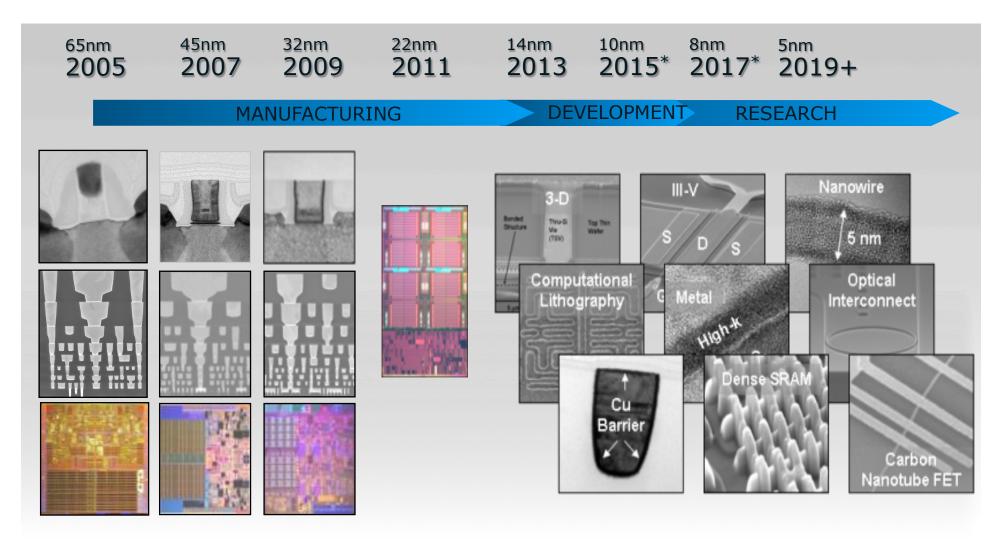
 10^5

- On a 100,000 sockets

Today's Exascale Expectation



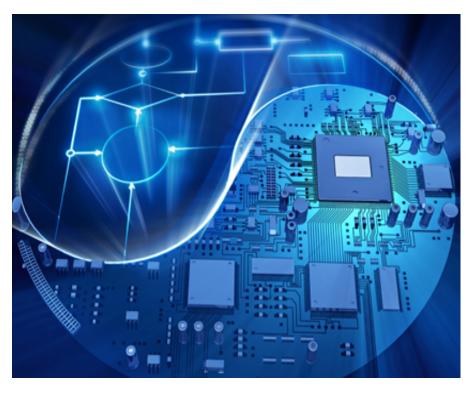
Moore's Law



^{*} All products, dates, and figures specified are preliminary based on current expectations, and are subject to change without notice.



Moore's Law - 22nm Tri-Gate



3rd Generation Intel® Core™ Processor **Family** (2012, codename

IvyBridge)



VS.

4004 (1971)



4,000X Faster

5,000X Less Energy / Transistor

50,000X Cheaper / Transistor

Source: Intel



